

Chokes for Power Lines

Material Data Sheet

Product Class:	Ring Core Double Choke	EPCOS		
	B82724B2***N***	RESPONDED ANALOGO OPAGE.OU		
	(Horizontal Version)			
Date	26.07.21			
IMDS ID if available				
Version:	03			

Parts with Full Compound

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese Zinc Ferrite	100	12645-49-7	41.6	
	Polymer	2C	Epoxy (EP)	100	25068-38-6	1.5	
	Heavy Metal	1C	Cu	100	7440-50-8	11.8	
	Polymer	2C	Polyurethane (PUR)	100	68400-67-9	0.7	
Encapsulation and Mounting	Polymer	24	Polycarbonate (PC)	89.8	25971-63-5	12.5	
		2A	Glass fiber	10	65997-17-3		
			PFBS	0.2	29420-49-3		
	Polymer	2C	Polyurethane (PUR)	100	68400-67-9	31.2	
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	
Termination		1C	Cu	62	7440-50-8		
	Heavy Metal	1C	Ni	18	7440-02-0	0.5	
		1C	Zn	20	7440-66-6		
	Heavy Metal	1C	Ni	100	7439-89-6		Х
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	
		•	•	•	Sum in total:	100.0	•
Size W x L x H [max. in mm] 32,6 x 33,6 x 25	Weight [approx. in g] 3546g	Part Number B82724B2152N020	B82724B2402N030 B82724B2182N021				

Parts with Economic Compound

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese Zinc Ferrite	100	12645-49-7	55.3	
	Polymer	2C	Epoxy (EP)	100	25068-38-6	1.8	
	Heavy Metal	1C	Cu	100	7440-50-8	14.1	
	Polymer	2C	Polyurethane (PUR)	100	68400-67-9	0.9	
Encapsulation and Mounting	Polymer	24	Polycarbonate (PC)	89.8	25971-63-5	16.4	
		2A	Glass fiber	10	65997-17-3		
			PFBS	0.2	29420-49-3		
	Polymer	2C	Polyurethane (PUR)	100	68400-67-9	10.6	
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	
Termination		1C	Cu	62	7440-50-8		
	Heavy Metal	1C	Ni	18	7440-02-0	0.7	
		1C	Zn	20	7440-66-6		
	Heavy Metal	1C	Ni	100	7439-89-6		Х
	Heavy Metal	1C	Sn	100	7440-31-5	0.1	
Sum in total:			100.0				



Size W x L x H [max. in mm]

32,6 x 33,6 x 25

Weight

[approx. in g] 35

B82724B2102N001 B82724B2202N001 B82724B2402N001 B82724B2501N001 B82724B2602N001

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*) others: .(not declarable or prohibited substances acc. GADSL)			

^{**)} typical mass percentage of substance

Important remarks:

- The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not
- This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid)

☑ no exemptions;

□ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

□ Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

□ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above